

DATA SHEET for LED

Part No.	LH30242	
Emitted Color	Lens Color	Chip Material
Red	White Diffused(Milky)	GaP

Absolute Maximum Rating of Each Segment ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Maximum Rating	Unit
Power Dissipation	P_M	45	mW
Pulse Forward Current (Duty 1/10 @ 1kHz)	I_{FP}	50	mA
Continuous Forward Current	I_F	15	mA
Reverse Voltage	V_R	6	V
Operation Temperature	T_{opr}	$-25^\circ\text{C} \sim 85^\circ\text{C}$	$^\circ\text{C}$
Storage Temperature	T_{stg}	$-40^\circ\text{C} \sim 100^\circ\text{C}$	$^\circ\text{C}$
Soldering Temperature : 2.0mm from Body for 3 seconds at 260°C			

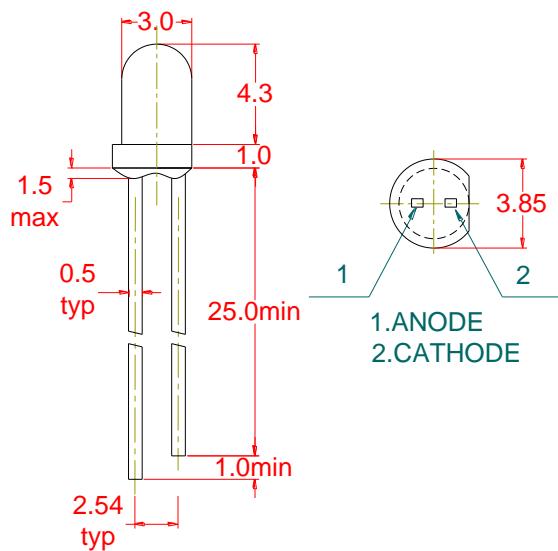
Electron-Optical Characteristics of Each Segment ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I_V	1.0	1.5		mcd	$I_F=10 \text{ mA}$
Forward Voltage	V_F		2.2	2.5	V	$I_F=20 \text{ mA}$
Reverse Current	I_R			50	μA	$V_R=5\text{V}$
Dominant Wavelength	λ_d		655		nm	$I_F=20 \text{ mA}$
Peak Emission Wavelength	λ_p		690		nm	$I_F=20 \text{ mA}$
Spectral Line Half Width	$\Delta\lambda$		60		nm	$I_F=20 \text{ mA}$
Viewing Angle	$2\theta_{1/2}$		40		deg	$I_F=20 \text{ mA}$

Note :

- 1) The luminous intensity data and λ_p is survey values with the machine JF-II, JS-2000.
- 2) $2\theta_{1/2}$ is the chip angle at which the luminous intensity half the axial luminous intensity.

Package Dimensions : 3mm Round Standard Resin Mold Type



Note : 1) All dimensions are in millimeters(mm)

2) Tolerance is $\pm 0.25\text{mm}$ unless otherwise note

Typical Characteristic Curves :

